

ABSTRACT OF THE DISCLOSURE

A surface mount chip package comprises a package housing made of a prescribed resin, which is formed to cover a semiconductor chip while avoiding a plurality of conductors extending from the semiconductor chip. A plurality of solder balls are arranged in the package housing in correspondence with a main surface of the semiconductor chip having an integrated circuit and are interconnected with the conductors respectively. An index serving as a marking member is arranged together with the solder balls so as to bring a directivity realized by the shape thereof when viewed in the thickness direction of the semiconductor chip. This allows a user to easily recognize the inclination and position of the package housing without using the solder balls in view of the index, thus establishing a prescribed positioning for an electrical test such as a probing test.